



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE
TITLE:  NI-780GS-4L	DOCUMENT NO: 98ASA00238D      REV: C	
	STANDARD: NON-JEDEC	
	SOT1805-1	23 FEB 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSION A1 IS MEASURED WITH REFERENCE TO DATUM T. THE POSITIVE VALUE IMPLIES THAT THE PACKAGE BOTTOM IS HIGHER THAN THE LEAD BOTTOM.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	Z	R.000	R.040	R0.00	R1.02
A1	.002	.008	0.05	0.20	AB	.145	.155	3.68	3.94
BB	.380	.390	9.65	9.91	t°	0°	8°	0°	8°
B1	.546	.562	13.87	14.27	aaa	.005		0.13	
CC	.125	.170	3.18	4.32	bbb	.010		0.25	
E	.035	.045	0.89	1.14	ccc	.015		0.38	
F	.003	.006	0.08	0.15					
L	.038	.046	0.97	1.17					
L1	.010 BSC		0.25 BSC						
J	.175 BSC		4.44 BSC						
M	.774	.786	19.66	19.96					
N	.772	.788	19.61	20.02					
R	.365	.375	9.27	9.53					
S	.365	.375	9.27	9.53					

© NXP SEMICONDUCTORS N. V.  
ALL RIGHTS RESERVED

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:

NI-780GS-4L

DOCUMENT NO: 98ASA00238D

REV: C

STANDARD: NON-JEDEC

SOT1805-1

23 FEB 2016